2SK2960

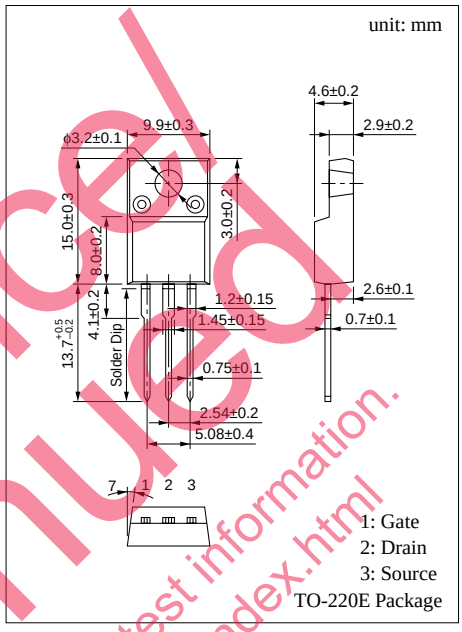
Silicon N-Channel Power F-MOS FET

■ Features

- Avalanche energy capacity guaranteed: EAS > 250mJ
- V_{GSS} = ±30V guaranteed
- High-speed switching: t_f = 55ns
- No secondary breakdown

■ Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply



■ Absolute Maximum Ratings (T_C = 25°C)

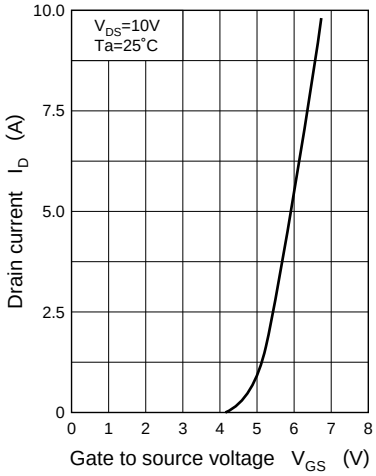
Parameter		Symbol	Ratings	Unit
Drain to Source breakdown voltage		V_{DSS}	400	V
Gate to Source voltage		V_{GSS}	±30	V
Drain current	DC	I_D	±10	A
	Pulse	I_{DP}	±20	A
Avalanche energy capacity		EAS*	250	mJ
Allowable power dissipation	T_C = 25°C	P_D	50	W
	Ta = 25°C		2	
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

* L = 5mH, I_L = 10A, 1 pulse

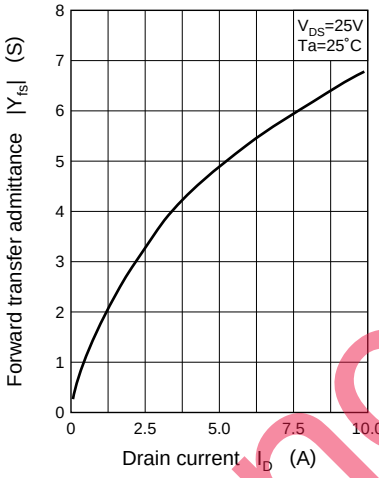
■ Electrical Characteristics (T_C = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	V_{DS} = 320V, V_{GS} = 0			0.1	mA
Gate to Source leakage current	I_{GSS}	V_{GS} = ±30V, V_{DS} = 0			±1	µA
Drain to Source breakdown voltage	V_{DSS}	I_D = 1mA, V_{GS} = 0	400			V
Gate threshold voltage	V_{th}	V_{DS} = 10V, I_D = 1mA	2		5	V
Drain to Source ON-resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 5A		0.4	0.52	Ω
Forward transfer admittance	$\|Y_{fs}\|$	V_{DS} = 10V, I_D = 5A	3	5		S
Diode forward voltage	V_{DSF}	I_{DR} = 10A, V_{GS} = 0			−1.5	V
Input capacitance (Common Source)	C_{iss}	V_{DS} = 10V, V_{GS} = 0, f = 1MHz		1400		pF
Output capacitance (Common Source)	C_{oss}			290		pF
Reverse transfer capacitance (Common Source)	C_{rss}			100		pF
Turn-on time (delay time)	$t_{d(on)}$	V_{GS} = 10V, I_D = 5A V_{DD} = 100V, R_L = 20Ω		25		ns
Rise time	t_r			50		ns
Turn-off time (delay time)	$t_{d(off)}$			170		ns
Fall time	t_f			55		ns

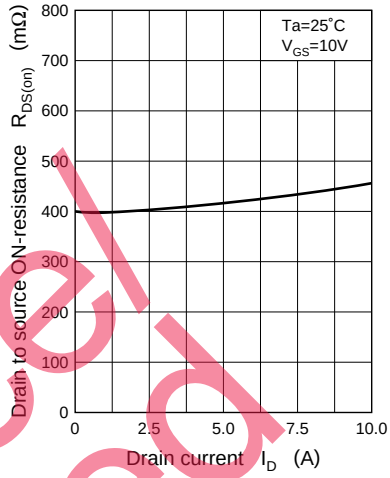
I_D — V_{GS}



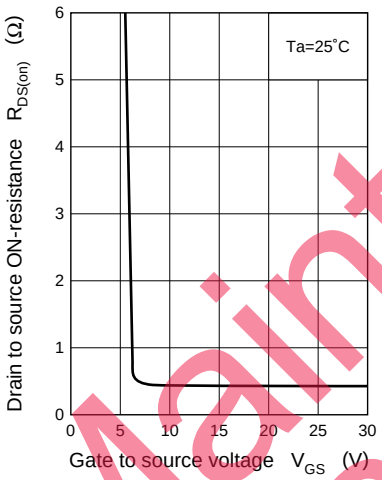
$|Y_{fs}|$ — I_D



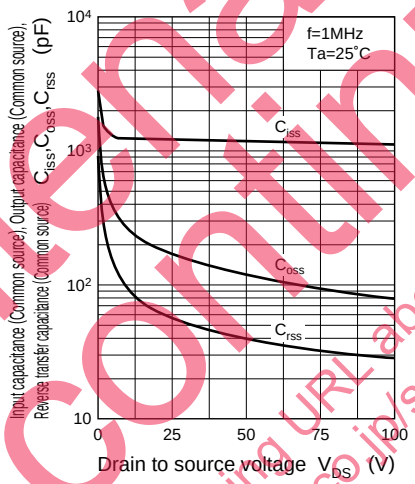
$R_{DS(on)}$ — I_D



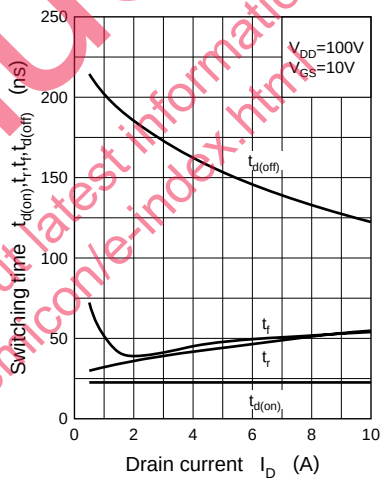
$R_{DS(on)}$ — V_{GS}



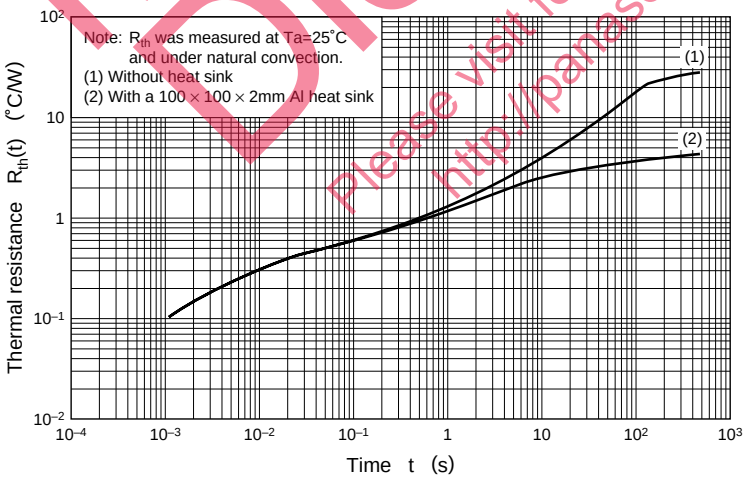
C_{iss}, C_{oss}, C_{rss} — V_{DS}



$t_{d(on)}$, t_r, t_f, $t_{d(off)}$ — I_D



$R_{th(t)}$ — t



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